

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

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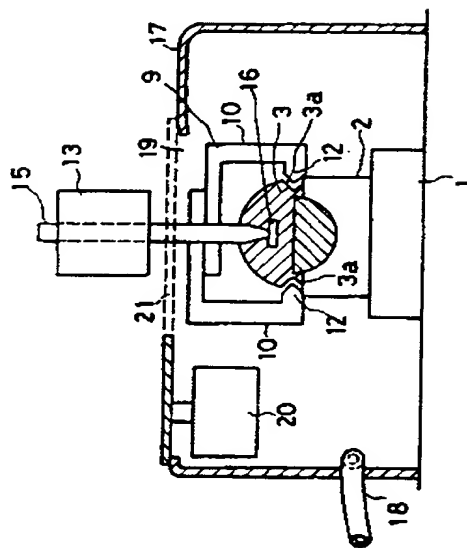
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TITLE : MOUNTING DEVICE



**ABSTRACT :** **PURPOSE:** To automatize bonding of a semiconductor chip to a stem by a method wherein the stem is placed on a placing stage by a stem carrying mechanism and the chip is fed on the stem by a mounting arm.

**CONSTITUTION:** The interior of a case 17 is full of inert gas which is supplied by a gas feed pipe 18. A stem 3 is grasped by a chucking mechanism 9, is put in the case 17 through an opening part 19 and is placed on a placing stage 2, while a semiconductor chip 16 attracted to the capillary 15 of a mounting arm 13 is fed on the stem 3 on the placing stage 2. Then, a shutter 21 is actuated by a rotary solenoid 20 and the opening part 19 is blocked. Then, a heating unit 1 is passed a current and a die-bonding of the semiconductor chip 16 to the stem 3 ends.

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